

HSB278S

Silicon Schottky Barrier Diode for Detector

REJ03G0596-0100 (Previous: ADE-208-1383) Rev.1.00 Apr 12, 2005

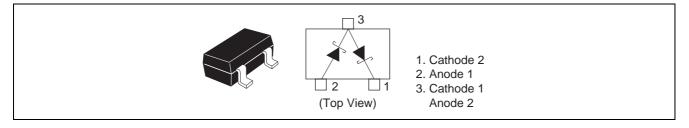
Features

- Low forward voltage, Low capacitance.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSB278S	S2	СМРАК	PTSP0003ZB-A (CMPAK)

Pin Arrangement





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V _{RRM}	30	V
Reverse voltage	V _R	30	V
Non-Repetitive peak forward surge current	I _{FSM} * ¹ * ²	200	mA
Peak forward current	I _{FM} * ²	150	mA
Average rectified current	lo * ²	30	mA
Junction temperature	Тј	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes: 1. 10 ms sine wave 1 pulse.

2. Per one device.

Electrical Characteristics *1

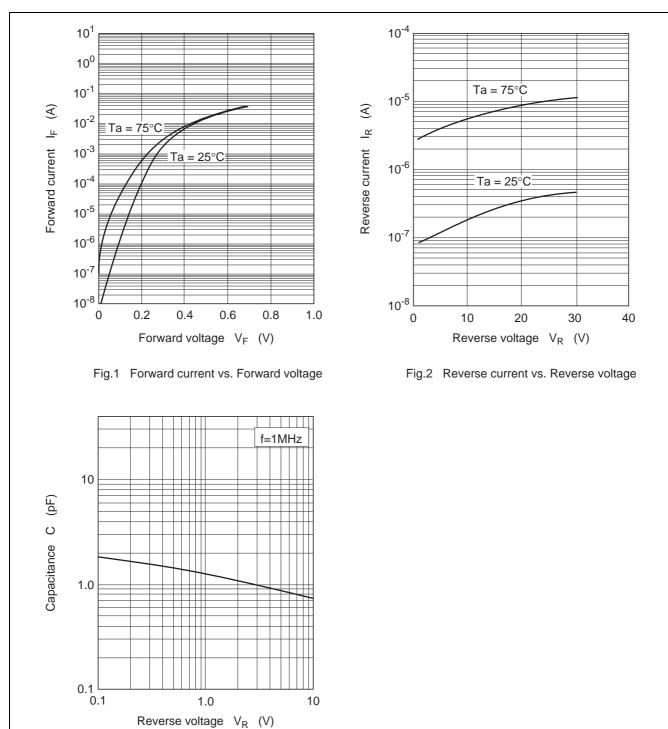
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _{F1}	—		0.30	V	I _F = 1 mA
	V _{F2}	—		0.95		I _F =30 mA
Reverse current	I _R	—		700	nA	V _R = 10 V
Capacitance *2	С	—		1.50	pF	$V_R = 1 V, f = 1 MHz$
ESD-Capability *1	—	100	_	—	V	C = 200 pF, $R_L = 0 \Omega$, Both forward and reverse direction 1 pulse.

Notes: 1. Per one device.

2. Failure criterion ; $I_R > 1.4 \ \mu A$ at V_R = 10 V



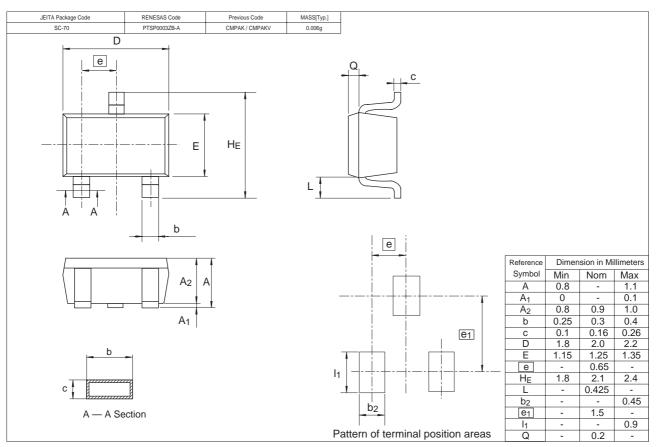


Main Characteristic

Fig.3 Capacitance vs. Reverse voltage



Package Dimensions





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